



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-03-01
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SPC58EC70E1E001Y	BV9I*FC80ABQ	A	ZY1A	2017-03-01
Amount		UoM	Unit type	ST ECOPACK Grade
260.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10x10x1	64	gull wing	
Comment	Package: TQFP 64 10x10x1.0 1.0 ExPad Down			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.001	die metallization	4

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BV91*FC80ABQ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	31.541	mg	supplier	die	Silicon (Si)	7440-21-3		28.442	mg	901747	109392
				supplier	metallization	Aluminium (Al)	7429-90-5		0.123	mg	3900	473
				supplier	metallization	Copper (Cu)	7440-50-8		0.385	mg	12206	1481
				supplier	metallization	Tantalum (Ta)	7440-25-7		2.125	mg	67373	8173
				supplier	metallization	Titanium (Ti)	7440-32-6		0.011	mg	349	42
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	63	8
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	31	4
				supplier	Passivation	Silicon Oxide	7631-86-9		0.452	mg	14331	1738
				Leadframe	Copper & its alloys	90.159	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						2.083	mg	23104	8012
supplier	alloy	Zinc (Zn)	7440-66-6						0.106	mg	1176	408
supplier	alloy	Phosphorous (P)	12185-10-3						0.027	mg	299	104
supplier	metallization	Silver (Ag)	7440-22-4						1.534	mg	17014	5900
Die attach	Other organic materials	4.199	mg	supplier	glue	Silver(Ag)	7440-22-4		3.275	mg	779948	12596
				supplier	glue	Phenolic Resin	9003-35-4		0.063	mg	15004	242
				supplier	glue	Ethylene glycol monobutyl ether acetate	112-07-2		0.168	mg	40010	646
				supplier	glue	Polymer with oxirane and Phenol	9003-36-5		0.630	mg	150036	2423
				supplier	glue	1,4-Butanedioldiglycidyl Ether	2425-79-8		0.063	mg	15002	242
Bonding wire	Other inorganic materials	0.448	mg	supplier	wire	Copper (Cu)	7440-50-8		0.439	mg	979911	1688
				supplier	wire	Palladium (Pd)	7440-05-3		0.009	mg	20089	36
Encapsulation	Other Organic Materials	130.207	mg	supplier	mold compound	Epoxy Resin A	25068-38-6		3.906	mg	29998	15023
				supplier	mold compound	Epoxy resin B	85954-11-6		9.114	mg	69996	35054
				supplier	mold compound	Silica fused (SiO3)	60676-86-0		109.375	mg	840009	420673
				supplier	mold compound	Carbon Black	1333-86-4		0.651	mg	5000	2504
Finishing	Other organic materials	3.446	mg	supplier	mold compound	Phenol Resin	29690-82-2		7.161	mg	54997	27542
				supplier	coating	Tin (Sn)	7440-31-5		3.446	mg	1000000	13254